SCBS026C - NOVEMBER 1988 - REVISED APRIL 1994

- State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ}
- 3-State True Outputs
- Back-to-Back Registers for Storage
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015
- Package Options Include Plastic Small-Outline Packages (DW), Ceramic Chip Carriers (FK) and Flatpacks (W), and Plastic and Ceramic 300-mil DIPs (JT, NT)

description

The 'BCT543 octal transceiver contains two sets of D-type latches for temporary storage of data flowing in either direction. Separate latch-enable ($\overline{\text{LEAB}}$ or $\overline{\text{LEBA}}$) and output-enable ($\overline{\text{OEAB}}$ or $\overline{\text{OEBA}}$) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable (\overline{CEAB}) input must be low in order to enter data from A or to output data from B. If \overline{CEAB} is low and \overline{LEAB} is low, the A-to-B latches are transparent; a subsequent low-to-high transition of \overline{LEAB} puts the A latches in the storage mode. With \overline{CEAB} and \overline{OEAB} both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar but requires using the \overline{CEBA} , \overline{LEBA} , and \overline{OEBA} inputs.

The SN54BCT543 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74BCT543 is characterized for operation from 0°C to 70°C.

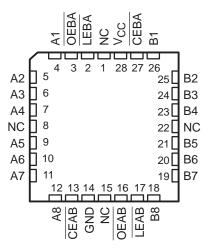
LEBA	1	Ο	24] <u>∨_{cc}</u>					
OEBA	2		23	CEBA					
A1 [22] B1					
A2 [21] B2					
A3 [5		20] B3					
A4 [6		19] B4					
A5 [18] B5					
A6 [17] B6					
A7 [16] B7					
A8 [10		15	B8					
CEAB	11		14	LEAB					
GND [12		13	OEAB					

SN54BCT543 ... JT OR W PACKAGE

SN74BCT543 . . . DW OR NT PACKAGE

(TOP VIEW)

SN54BCT543 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

FUNCTION	TABLE [†]
----------	--------------------

	INPU	OUTPUT		
CEAB	LEAB	OEAB	Α	В
Н	Х	Х	Х	Z
X	Х	Н	Х	Z
L	Н	L	Х	в ₀ ‡
L	L	L	L	L
L	L	L	Н	Н

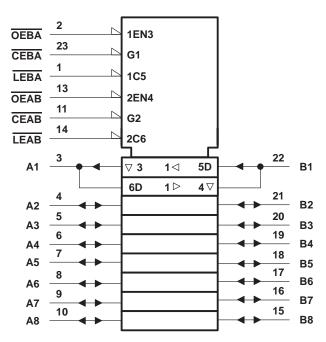
[†] A-to-B data flow is shown; <u>B-to-A flow</u> control is the same except that it uses CEBA, LEBA, and OEBA.

[‡]Output level before the indicated steady-state input conditions were established.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

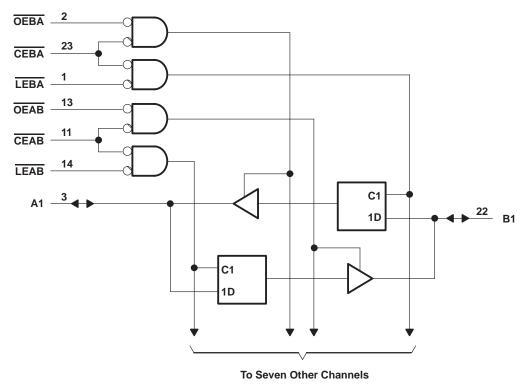
SCBS026C - NOVEMBER 1988 - REVISED APRIL 1994

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



Pin numbers shown are for the DW, JT, NT, and W packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range: Control inputs (see Note 1)	\ldots — 0.5 V to 7 V
I/O ports (see Note 1)	
Voltage range applied to any output in the disabled or power-off state, VO	– 0.5 V to 7 V
Voltage range applied to any output in the high state, VO	$\dots - 0.5$ V to V _{CC}
Input clamp current, IIK	
Current into any output in the low state: SN54BCT543	96 mA
SN74BCT543	128 mA
Operating free-air temperature range: SN54BCT543	– 55°C to 125°C
SN74BCT543	0°C to 70°C
Storage temperature range	$\dots - 65^{\circ}C$ to $150^{\circ}C$

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions

		SN54BCT543		SN74BCT543			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
Iк	Input clamp current			-18			-18	mA
IOH	High-level output current			-12			-15	mA
IOL	Low-level output current			48			64	mA
T _A	Operating free-air temperature	-55		125	0		70	°C



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN	54BCT5	43	SN74BCT543			
				MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
VIK		V _{CC} = 4.5 V,	lı = -18 mA			-1.2			-1.2	V
			I _{OH} = -3 mA	2.4	3.3		2.4	3.3		
VOH		$V_{CC} = 4.5 V$	I _{OH} = -12 mA	2	3.2					V
			I _{OH} = -15 mA				2	3.1		
Vai		V _{CC} = 4.5 V	I _{OL} = 48 mA		0.38	0.55				V
VOL		VCC = 4.5 V	I _{OL} = 64 mA					0.42	0.55	V
lj		V _{CC} = 5.5 V,	V _I = 5.5 V			0.4			0.4	mA
. +	A or B port		V. 07V			70			70	۸
ι _{Η‡}	Control input	V _{CC} = 5.5 V,	V ₁ = 2.7 V			20			20	μA
. +	A or B port					-0.65			-0.65	mA
IIL‡	Control input	V _{CC} = 5.5 V,	V _I = 0.5 V			-0.6			-0.6	ΠA
los§		V _{CC} = 5.5 V,	$V_{O} = 0$	-100		-225	-100		-225	mA
ICCL	A or B port	V _{CC} = 5.5 V			45	71		45	71	mA
ІССН	A or B port	V _{CC} = 5.5 V			5	8		5	8	mA
ICCZ	A or B port	V _{CC} = 5.5 V			9	15		9	15	mA
Ci	Control input	V _{CC} = 5 V,	V _I = 2.5 V or 0.5 V		6			6		pF
C _{io}	A or B port	V _{CC} = 5 V,	V _O = 2.5 V or 0.5 V		16			16		pF

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

 \ddagger For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

			V _{CC} =	V _{CC} = 5 V, T _A = 25°C		SN54BCT543		SN74BCT543	
			MIN	MAX	MIN	MAX	MIN	MAX	
tw	Pulse duration, LEAB or LEBA low		7		8		7		ns
t _{su}	Setup time, data before \overline{LEAB} or \overline{LEBA}	High or low	4.5		5.5		4.5		ns
th	Hold time, data after \overline{LEAB} or \overline{LEBA}	High or low	1.5		1.5		1.5		ns



SN54BCT543, SN74BCT543 OCTAL REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS SCBS026C – NOVEMBER 1988 – REVISED APRIL 1994

switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)			V _{CC} = 5 V, C _L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T _A = 25°C			V_{CC} = 4.5 V to 5.5 V, C_{L} = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T_{A} = MIN to MAX [†]			
			Έ	3CT543		SN54B	CT543	SN74B	CT543	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	A or B	B or A	2	5.7	7.5	2	9.9	2	8.8	
^t PHL	AUID	BUTA	2	6.3	8.2	2	9.7	2	9.6	ns
^t PLH	LE	A or B	2	8.2	10.3	2	13.9	2	12.9	ns
^t PHL	LE	AUID	2	8.5	10.6	2	13.2	2	12.7	
^t PZH	OE	A or D	1	6.8	8.6	1	11.4	1	10.7	
^t PZL	ÛE	A or B	1	8.7	10.8	1	12.8	1	12.3	ns
^t PHZ		A an D	1	5.5	7.2	1	8.8	1	8.1	
^t PLZ	OE	A or B	1	4.7	6.4	1	8.1	1	7.2	ns
^t PZH		A or P	1	7.6	9.8	1	12.8	1	12	
^t PZL	CE	A or B	1	9.5	11.6	1	13.8	1	13.5	ns
^t PHZ	CE	A or D	1	5.8	7.5	1	9.3	1	8.5	
^t PLZ		A or B	1	4.8	6.7	1	8.4	1	7.6	ons ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9087001M3A	ACTIVE	LCCC	FK	28	1	TBD	Call TI	Level-NC-NC-NC
5962-9087001MKA	ACTIVE	CFP	W	24	1	TBD	Call TI	Level-NC-NC-NC
5962-9087001MLA	ACTIVE	CDIP	JT	24	1	TBD	Call TI	Level-NC-NC-NC
SN74BCT543DW	ACTIVE	SOIC	DW	24	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74BCT543DWR	ACTIVE	SOIC	DW	24	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74BCT543NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SNJ54BCT543FK	ACTIVE	LCCC	FK	28	1	TBD	Call TI	Level-NC-NC-NC
SNJ54BCT543JT	ACTIVE	CDIP	JT	24	1	TBD	Call TI	Level-NC-NC-NC
SNJ54BCT543W	ACTIVE	CFP	W	24	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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MECHANICAL DATA

MCER004A - JANUARY 1995 - REVISED JANUARY 1997

JT (R-GDIP-T**)

CERAMIC DUAL-IN-LINE

24 LEADS SHOWN



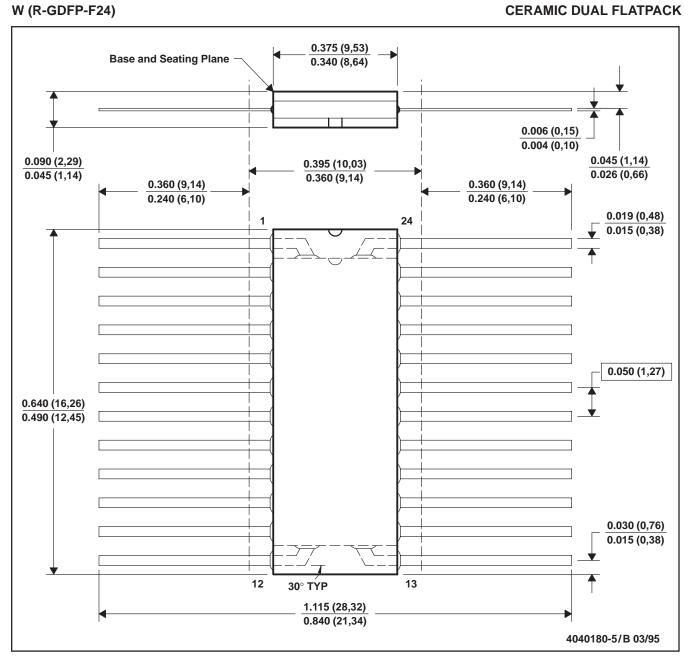
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB



MECHANICAL DATA

MCFP007 - OCTOBER 1994



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. This package can be hermetically sealed with a ceramic lid using glass frit.

- D. Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
- E. Index point is provided on cap for terminal identification only.



MLCC006B - OCTOBER 1996

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



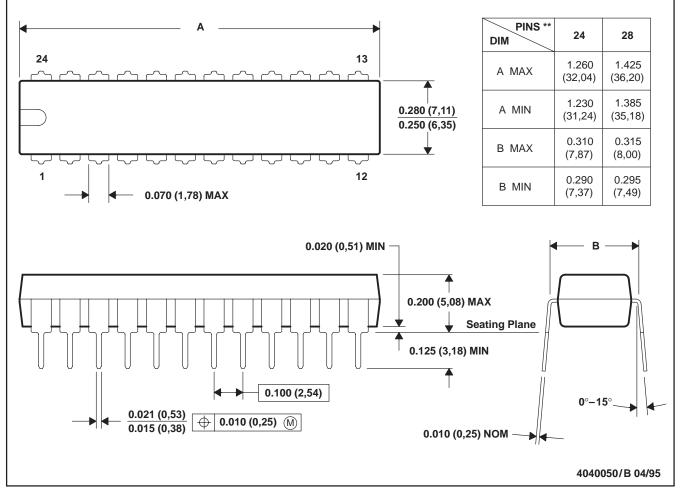
MECHANICAL DATA

MPDI004 - OCTOBER 1994

NT (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters). B. This drawing is subject to change without notice.



DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.



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Mailing Address:

Texas Instruments

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